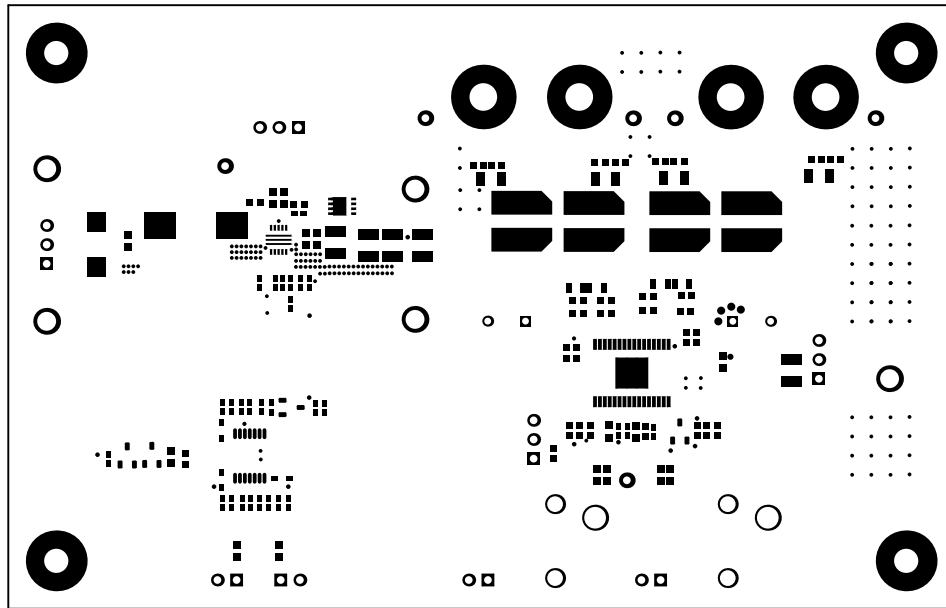
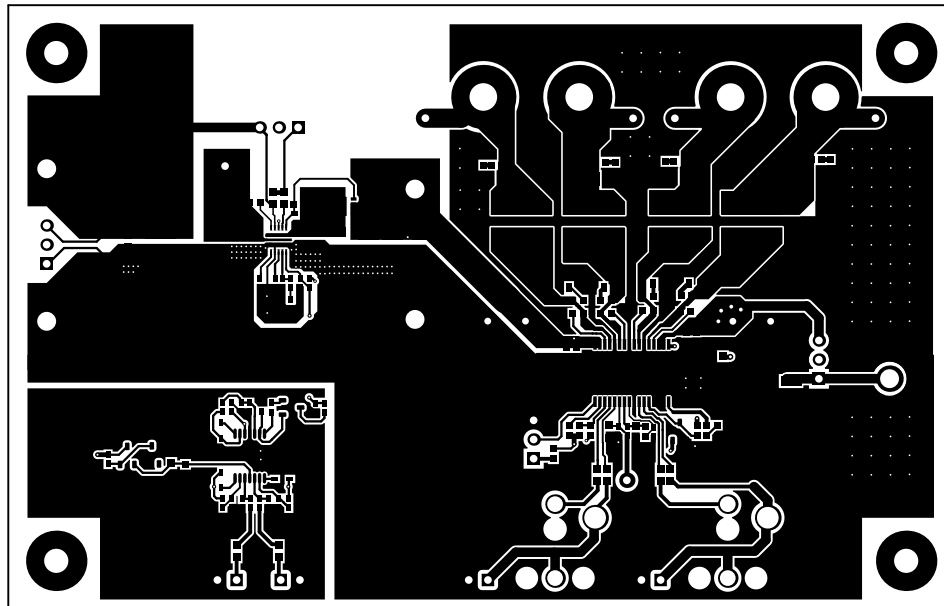


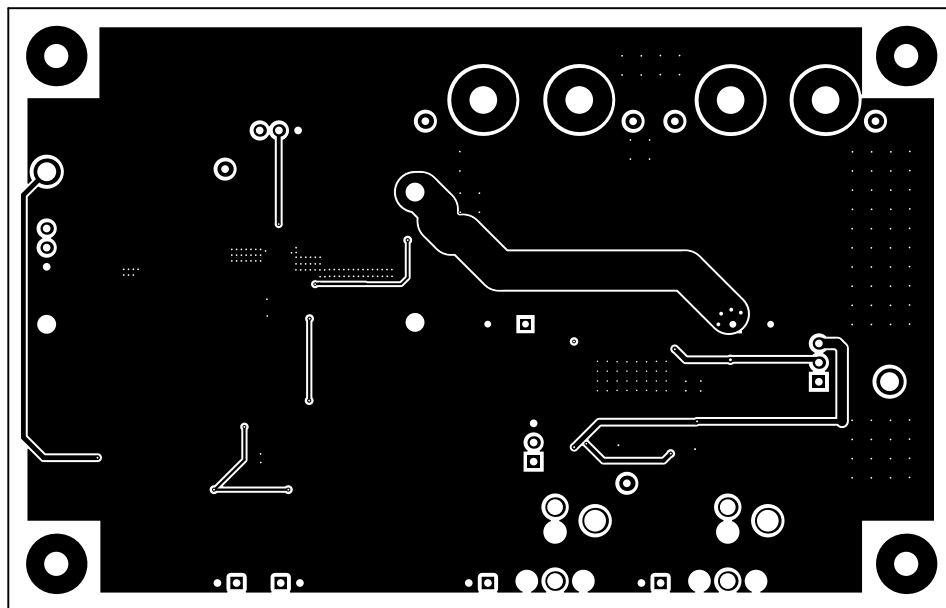
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP15036 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | TID #: .TID | | |
| PLOT NAME = Top Overlay | GENERATED: 9/23/2017 11:55:37 AM | TEXAS INSTRUMENTS | |



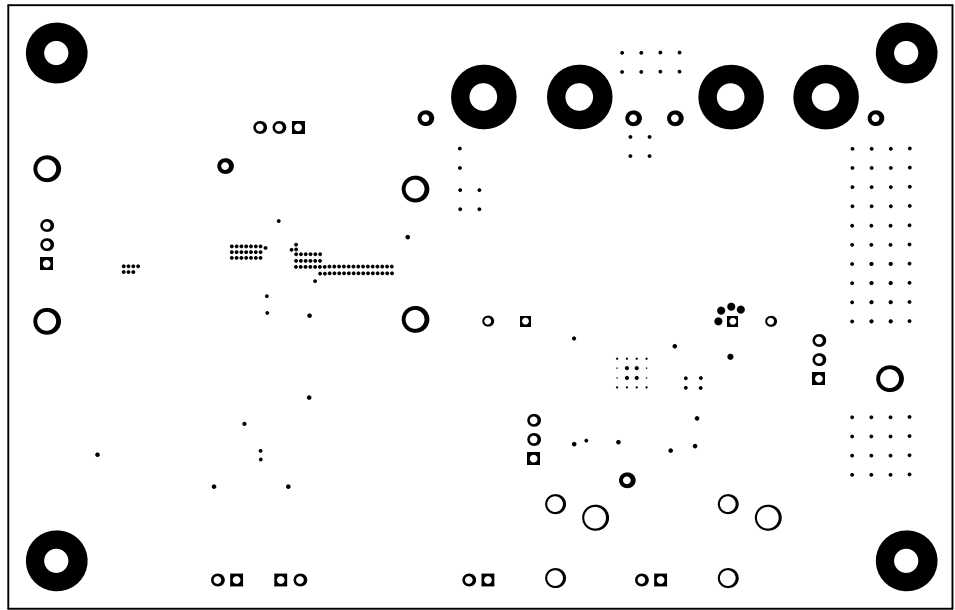
| | | | |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP15036 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | TID #: .TID | | |
| PLOT NAME = Top Solder Mask | GENERATED: 9/23/2017 | 11:55:38 AM | TEXAS INSTRUMENTS |



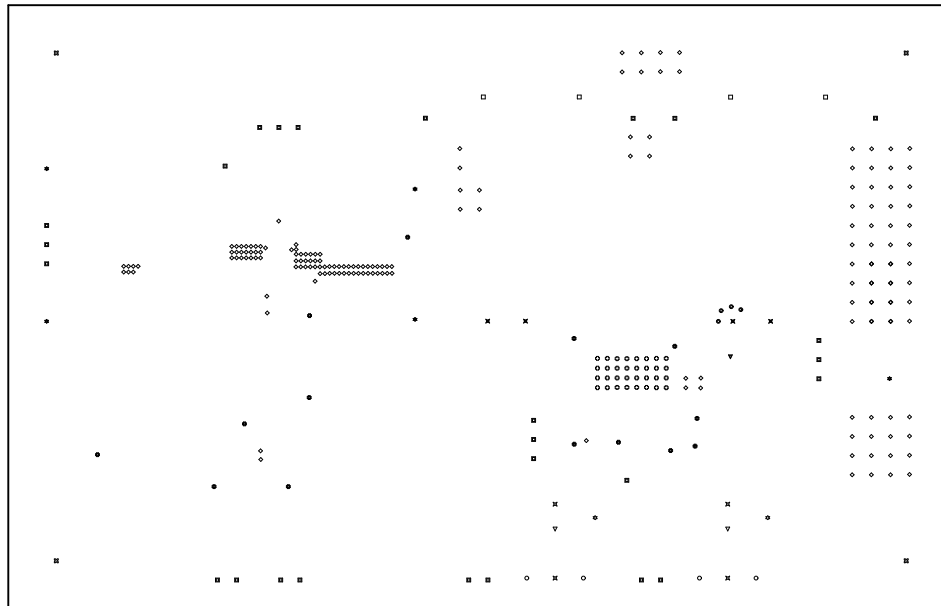
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP15036 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer | TID #: .TID | | |
| PLOT NAME = Top Layer | GENERATED: 9/29/2017 11:56:39 AM | TEXAS INSTRUMENTS | |



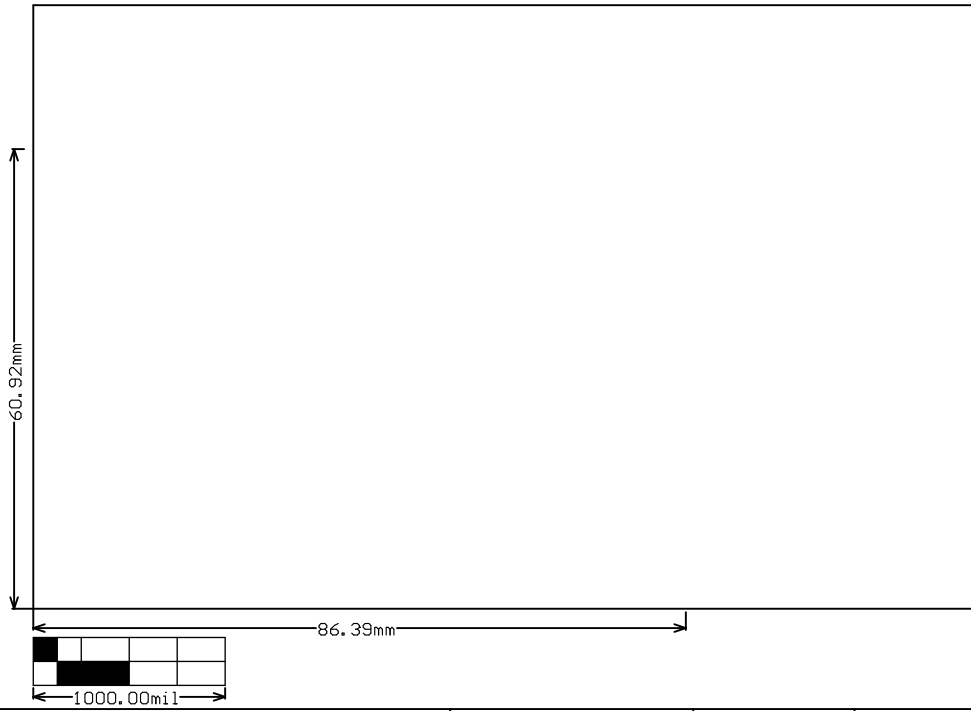
| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP15036 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | TID #: .TID | | |
| PLOT NAME = Bottom Layer | GENERATED : 9/29/2017 11:55:41 AM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP15036 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | TID #: .TID | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 9/29/2017 11:55:42 AM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|-----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP15036 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | TID #: .TID | | |
| PLOT NAME = Drill Drawing | GENERATED : 9/29/2017 | 11:55:43 AM | TEXAS INSTRUMENTS |



| | | | |
|----------------------------------|-----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP15036 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | TID #: .TID | | |
| PLOT NAME = Board Dimensions | GENERATED : 9/29/2017 | 11:55:44 AM | TEXAS INSTRUMENTS |

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